SP	FC	IFI	CA	NS
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CUSTOMER . PTC

SAMPLE CODE · S05D00055-00

MASS PRODUCTION CODE . P05D00055-00

SAMPLE VERSION . 01

SPECIFICATIONS EDITION . 003

DRAWING NO. (Ver.) : LMD- P05D00055-00 (Ver.003)

PACKAGING NO. (Ver.) : PKG- P05D00055-00 (Ver.002)

# **Customer Approved**

Date:

Approved	Checked	Designer
林裘中	張慶源	廖志豪
Daniel Lin	Yuan Chang	Rex Liao

Preliminary specification for design input

Specification for sample approval

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# **History of Version**

Date (mm / dd / yyyy)	Ver.	Edi.	Description	Page	Design by
04/21/2017	01	001	Preliminary	-	Rex
09/14/2017	01	002	First Sample SPEC	-	Rex
01/10/2018	01	003	Second Sample SPEC  Modify Total thickness.	-	Rex

Total: 20Page



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Appendix: 1. LCM Drawing



# 1. SPECIFICATIONS

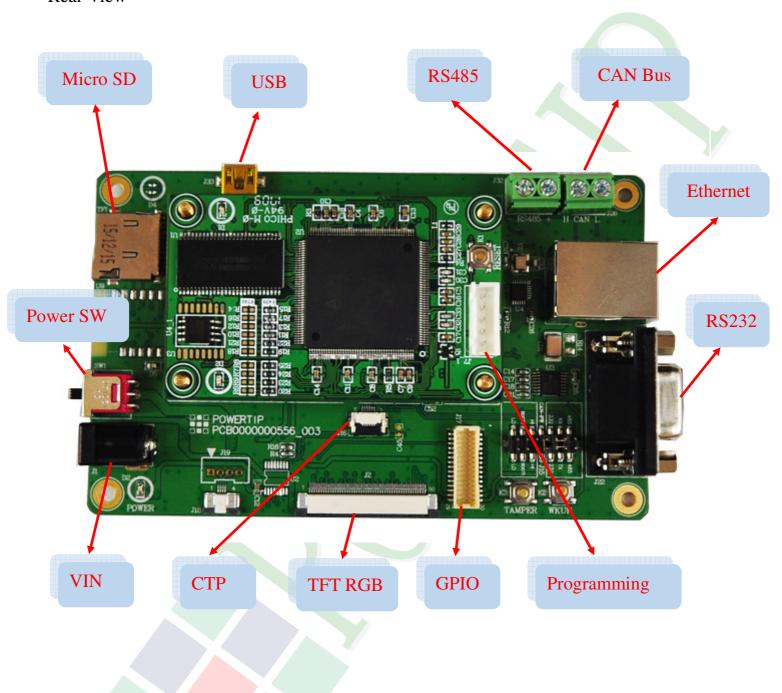
### 1.1 Features

### **Hardware**

CPU	RISC Processor	Cortex-M4 STM32F429IGT6 (180MHz)
	On Board RAM	8MB SDRAM
Memory	On Board ROM	16MB SPI Flash
	External Storage	1x Micro SD (under 32G)
Display	Resolution	Up to 1024 RGB x 768
2 iopiay	Touch Panel	Projected Capacitive Touch
	USB	1x USB2.0 Host
	COM Port	1x RS485 or RS232
	CAN BUS	2.0B Active
Interface	Alarm	Buzzer
	Ethernet	IEEE 1588v2
	RTC	Supported
	GPIO	22pin GPIO
Power Input	DC	7V ~ 36V



Rear View



NOTE: If you have any request, please feel free to contact us.



# 1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	128.0(W) x 75.6(L) x 22.4MAX	mm

# 1.3 Absolute Maximum Ratings

Ta = 25°C

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply	VIN	4	-0.3	40.0	V
Operating Temperature	TOP		-20	70	℃
Storage Temperature	T <sub>ST</sub>		-30	80	℃
Humidity	H <sub>D</sub>	Ta=60 °C	10	90	%RH

# 1.4 DC Electrical Characteristics

Ta = 25°C

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage	VIN	(1)	7	-	36	٧
Power Consumption of System	Pvin	VIN=9V (2)	ı	ı	4.1	W

Note 1: VIN is to connect to 'J1' connector at board.

2. Connect with PH800480T024-IHC (PTC Product) for test power consumption.



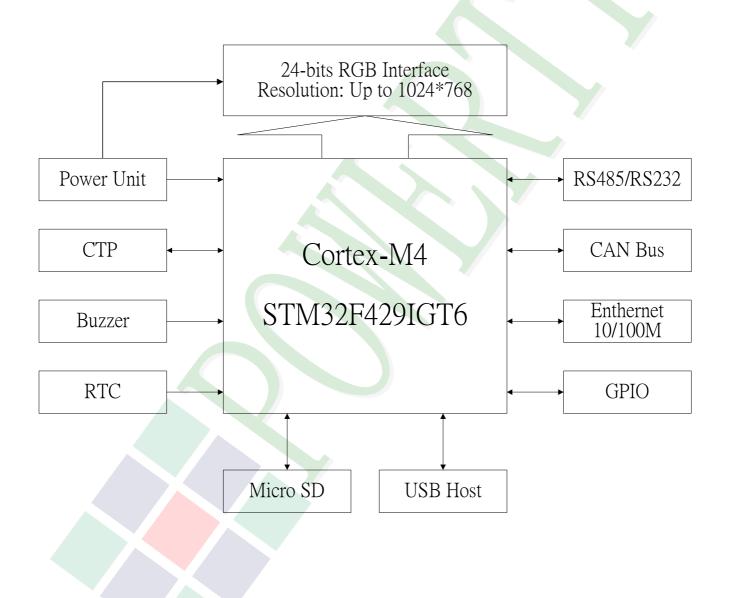
# 2. MODULE STRUCTURE

# 2.1 Counter Drawing

### 2.1.1 LCM Mechanical Diagram

\* See Appendix

### 2.1.2 Block Diagram

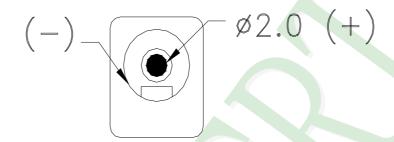




# 2.2 Interface Pin Description

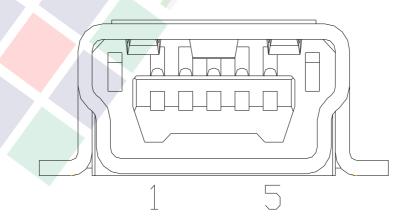
# J1 --- Power Supply

Pin No.	Symbol		Function
+	VIN	DC Power Supply	
-	GND	Ground	



# J33 --- USB 2.0 Mini USB B type

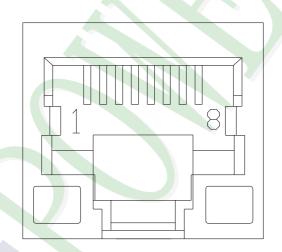
Pin No.	Symbol	Function
1	5V	5V
2	D-	Data – (Data M)
3	D+	Data + (Data P)
4	NC	NC
5	GND	Ground





### **J37 --- Ethernet IEEE 1588v2**

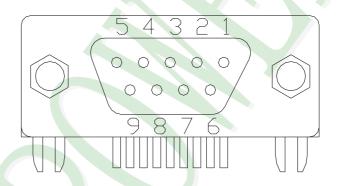
Pin No.	Symbol	Function
1	RX+	Data Receive
2	RX-	Data Receive
3	TX+	Data Transmit
4	3V3	Power Supply.
5	3V3	Power Supply.
6	TX-	Data Transmit
7	NC	Not Used.
8	GND	Ground.





# J22 --- RS232 DB9 Female Type

Pin No.	Symbol	Function
1	NC	Not Used.
2	RXD1	Transmit from STM32. Receiver for customer.
3	TXD1	Receiver for STM32. Transmit from customer.
4	NC	Not Used.
5	GND	Ground
6	NC	Not Used.
7	NC	Not Used.





### **J26** --- **CAN BUS**

Pin No.	Symbol		Function
1	CANL	Low-Level CAN bus line.	
2	CANH	High-Level CAN bus line.	

### J32 --- RS485

Pin No.	Symbol	Function
1	А	Non-inverting transmitter output and non-inverting receiver input.
2	В	Inverting transmitter output and inverting receiver input.

# J16 --- CTP (Pitch0.5mm 6pin Bottom contact)

Pin No.	Symbol	Function
1	GND	Ground.
2	3V3	Power Supply.
3	I2C_SCL	I2C SCL for CTP.
4	I2C_SDA	I2C SDA for CTP.
5	CTP_INT	Interrupt Signal for CTP.
6	CTP_RST	Reset Signal for CTP.



# J2 --- TFT Signal (Pitch 0.5mm 50pin Upper contact)

Pin No.	Symbol	Function
1	GND	Ground.
2	3V3	Power Supply (+3.3V).
3	3V3	Power Supply (+3.3V).
4	5V	Power Supply (+5.0V).
5	5V	Power Supply (+5.0V).
6	PWM	PWM Signal.
7	GND	Ground.
8	R0	Red Data.
9	R1	Red Data.
10	R2	Red Data.
11	R3	Red Data.
12	GND	Gground.
13	R4	Red Data.
14	R5	Red Data.
15	R6	Red Data.
16	R7	Red Data.
17	GND	Ground.
18	G0	Green Data.
19	G1	Green Data.
20	G2	Green Data.
21	G3	Green Data.
22	GND	Ground.
23	G4	Green Data.
24	G5	Green Data.
25	G6	Green Data.
26	<b>G</b> 7	Green Data.
27	GND	Ground.
28	В0	Blue Data.
29	B1	Blue Data.
30	B2	Blue Data.



Pin No.	Symbol	Function	
31	В3	Blue Data.	
32	GND	Ground.	
33	B4	Blue Data.	
34	B5	Blue Data.	
35	B6	Blue Data.	
36	B7	Blue Data.	
37	GND	Ground.	
38	HS	Line synchronization signal. Horizontal Sync.	
39	VS	Frame synchronization signal. Vertical Sync.	
40	GND	Ground.	
41	DE	Data Enable.	
42	GND	Power Ground.	
43	DCLK	Sample clock. Data will be latched at the falling edge of DCLK.	
44	GND	Power ground.	
45	SPI_CS	SPI /CS Signal.	
46	SPI_SDA	SPI SDA Signal.	
47	SPI_SCK	SPI SCK Signal.	
48	DIS_CTL	Display Enable Control.	
49	/RESET	Reset Signal.	
50	GND	Power ground.	



# J17 --- GPIO Signal (Pitch 1.0mm)

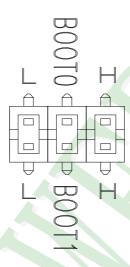
Pin No.	Symbol	Function
1	PB6	Connect with STM32 pin164 (PB6).
2	PB7	Connect with STM32 pin165 (PB7).
3	PA4	Connect with STM32 pin50 (PA4).
4	PD3	Connect with STM32 pin145 (PD3).
5	PA5	Connect with STM32 pin51 (PA5).
6	PD5	Connect with STM32 pin147 (PD5).
7	PA8	Connect with STM32 pin119 (PA8).
8	PD7	Connect with STM32 pin151 (PD7).
9	PA15	Connect with STM32 pin138 (PA15).
10	PI1	Connect with STM32 pin132 (PI1).
11	PE3	Connect with STM32 pin2 (PE3).
12	PI3	Connect with STM32 pin134 (PI3).
13	PE2	Connect with STM32 pin1 (PE2).
14	PI5	Connect with STM32 pin174 (PI5).
15	PB3	Connect with STM32 pin161 (PB3).
16	PI6	Connect with STM32 pin175 (PI6).
17	PB4	Connect with STM32 pin162 (PB4).
18	PI7	Connect with STM32 pin176 (PI7).
19	PC2	Connect with STM32 pin34 (PC2).
20	PI8	Connect with STM32 pin7 (PI8).
21	PC6	Connect with STM32 pin115 (PC6).
22	PI11	Connect with STM32 pin13 (PI11).
23	GND	Power ground.
24	GND	Power ground.
25	GND	Power ground.
26	GND	Power ground.
27	3V3	Power Supply.(+3.3V)
28	3V3	Power Supply.(+3.3V)
29	5V	Power Supply.(+5.0V)
30	5V	Power Supply.(+5.0V)



# J9 --- Boot Mode Setting (Pitch 2.0mm)

MODE	BOOST0	BOOST1
User Flash	L	X
System Memory	Н	L
Embedded SRAM	Н	Н

Note: X—Don't Care.



# J15 --- Power Supply For RS485 and CAN BUS (Pitch 2.0mm)

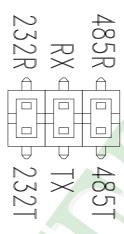
Short J15 ---- +5V connect with RS485 and CAN BUS Unit.

Open J15 ---- +5V disconnect with RS485 and CAN BUS Unit.



# J14 --- RS232/RS485 Mode Setting (Pitch 2.0mm)

MODE	RX	TX
RS-232	232R	232T
RS-485	485R	485T



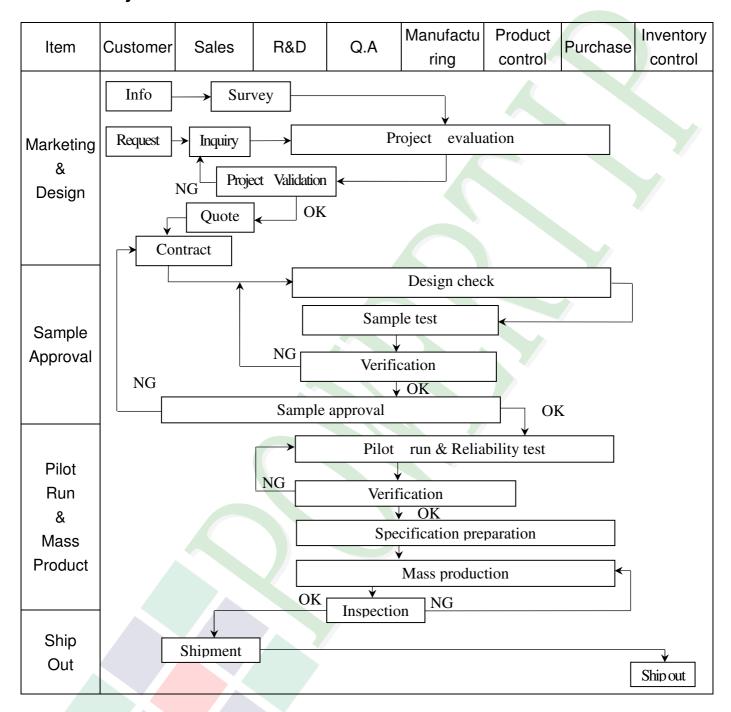
# J7 --- Programming (Pitch 2.5mm)

Pin No.	Symbol	Function
1	NRST	JTAG Test nReset
2	TCK	JTAG Test Clock
3	GND	Power ground.
4	TMS	JTAG Test Mode Selection
5	3V3	Power Supply (+3.3V).

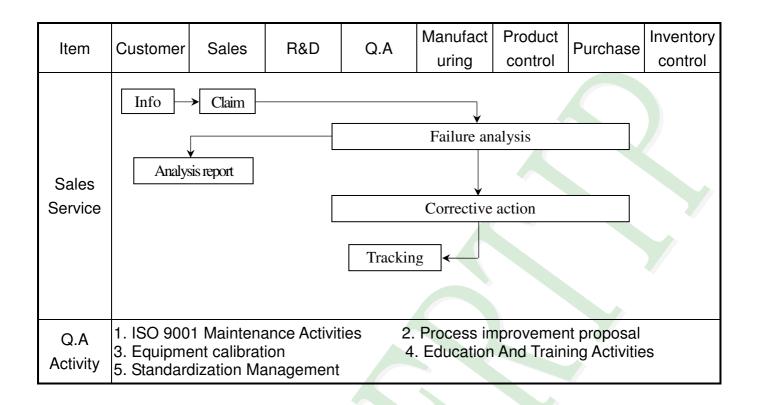


### 3. QUALITY ASSURANCE SYSTEM

### 3.1 Quality Assurance Flow Chart









# 4. RELIABILITY TEST

4.1 Reliability Test Condition

NO.	TEST ITEM	TEST CONDITION
1	High Temperature Storage Test	Keep in +70 ±2℃ 96 hrs Surrounding temperature, then storage at normal condition 4hrs.
2	Low Temperature Storage Test	Keep in −20 ±2°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.
3	High Temperature / High Humidity Storage Test	Keep in +60℃ / 90% R.H duration for 96 hrs Surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer)
4	Temperature Cycling Storage Test	$-20^{\circ}\text{C} \rightarrow +25^{\circ}\text{C} \rightarrow +70^{\circ}\text{C} \rightarrow +25^{\circ}\text{C}$ $(30\text{mins})  (5\text{mins})  (5\text{mins})$ $10 \text{ Cycle}$ Surrounding temperature, then storage at normal condition 4hrs.
5	Vibration Test (Packaged)	<ol> <li>Sine wave 10~55 Hz frequency (1 min)</li> <li>The amplitude of vibration :1. 5 mm</li> <li>Each direction (X \cdot Y \cdot Z) duration for 2 Hrs</li> </ol>
6	Drop Test (Packaged)	Packing Weight (Kg)         Drop Height (cm)           0 ~ 45. 4         122           45. 4 ~ 90. 8         76           90. 8 ~ 454         61           Over 454         46   Drop direction : ※1 corner / 3 edges / 6 sides each 1 times



### 5. PRECAUTION RELATING PRODUCT HANDLING

#### **5.1 SAFETY**

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

#### 5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully ,do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is 320±10°C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM.

### **5.3 STORAGE**

- 5.3.1 Store the panel or module in a dark place where the temperature is  $25^{\circ}$ C  $\pm 5^{\circ}$ C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

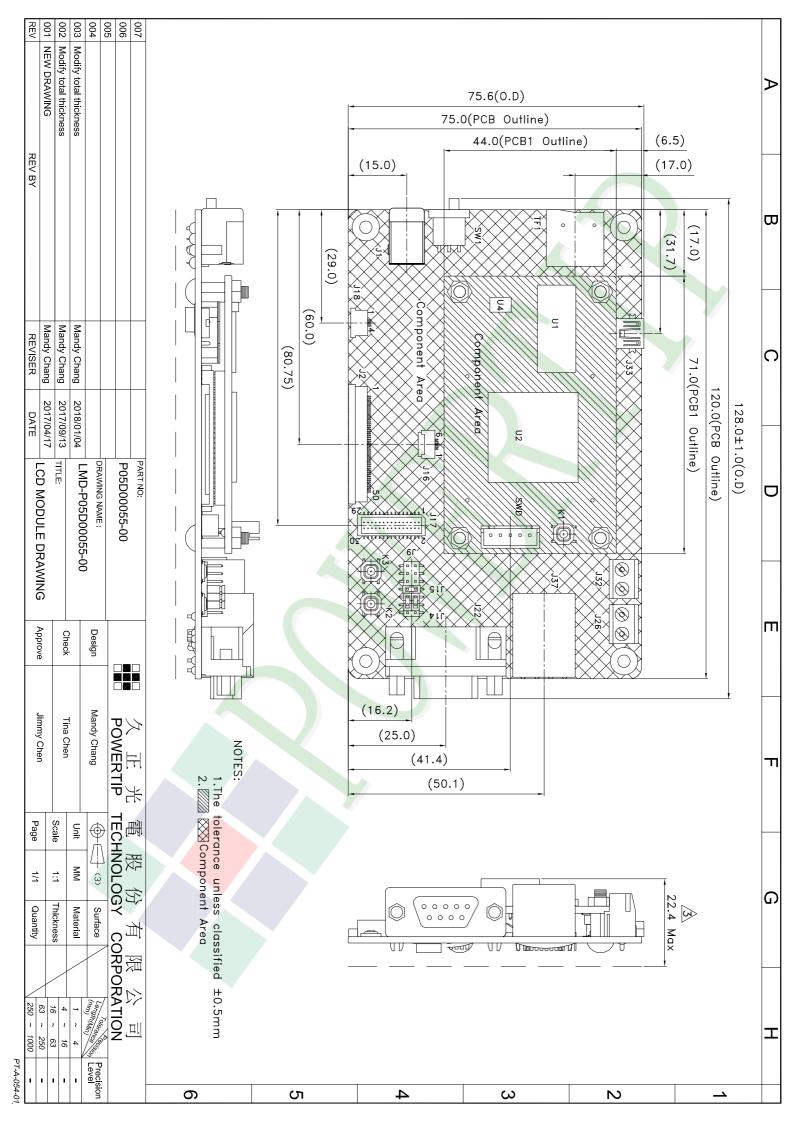
#### **5.4 TERMS OF WARRANTY**

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.



#### Approve Check Contact Ver.002 LCM包裝規格書 Jimmy Tina Mandy Documents NO. PKG-P05D00055-00 LCM Packaging Specifications 1.包裝材料規格表 (Packaging Material): (per carton) No. Item Model Dimensions (mm) 1Pcs Weight Quantity Total Weight P05D00055-00 1 成品 (LCM) /2\ 128.0 X 75.6 X 21.4 0.0847 36 3.0492 2 靜電袋(1)Antistatic Bag 36 BAG240170ARABA 240 X 170 0.0048 0.1728 3 氣泡袋(2)Bubble Bag BAG170150BRABA 170 X 150 0.0045 36 0.162 0.014 42 A4隔板(3)A4 Partition 245 X 70 X 2.5 0.588 4 BX24500070BNBA 293 X 70 X 2.5 24 5 B4隔板(4)B4 Partition BX29300070BLBA 0.012 0.288 海綿墊(5)Foam Rubber Cushion 0.02 12 6 OTFOAM00006ABA 290 X 240 X 10 0.24 0.263 7 C3内盒(6)Product Box BX31025510AABA 310 X 255 X 100 6 1.578 外紙箱(7)Carton 1.092 8 BX52732536CCBA 527 X 325 X 360 1 1.092 9 2.一整箱總重量 (Total LCD Weight in carton ): <sup>22</sup>7.17 Kg±10% 3.單箱數量規格表 (Packaging Specifications and Quantity): (1)Quantity Of Spacer: A4隔板 X 7, B4隔板 X 4 (2) Total LCM quantity in carton: quantity per box x no of boxes 36 (5) 海綿墊 Foam Rubber Cushion (1)靜電袋+(2)氣泡袋+LCM Antistatic Bag+Bubble Bag+LCM (3)(4)隔板 Partition (註 Remark 1) 삯 (5) 海綿墊 ۱ŀ (7)外紙箱 Foam Rubber Cushion Carton (6) C3內盒 Product Box 特 記 事 項 (REMARK) 1. LCM排放示意圖(前後間隔不放置): 1. LCM placed as figure showing:

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MCIMX53-START-R TWR-K65F180M KEA128BLDCRD CC-ACC-MMK-2443 STM8L1528-EVAL YSPKS5D9E10 YGRPEACHFULL
TWR-MC-FRDMKE02Z TWR-K80F150M CY14NVSRAMKIT-001 EVALSPEAR320CPU EVB-SCMIMX6SX MAXWSNENV# FM064L-S6E1C3 MAX32600-KIT# TMDX570LS04HDK Z32F3840100KITG LS1021A-IOT-B SK-FM3-100PMC-MB9BF516N TXSD-SV70
YSTBS3A3E10 YR8A77430HA02BG STM3240G-USB/NMF OM13080UL EVAL-ADUC7120QSPZ CYDP-KIT-13638 OM13063UL
ATAVRPARROT OM13090UL YSPEHMI1S20 TXSD-SV71 YGRPEACHNORMAL SK-FM3-176PMC-ETHERNET HVP-KV11Z75M
OM13076UL LX2RDBKIT2-25G